42E Ъ 7964142 0010482 SMGK

DRAM MODULES

-46-23-1

4M×9 CMOS DRAM Memory Module

FEATURES

• Performance range:

KMM594000

	trac	tcac	t _{RC}
KMM594000-8	80ns	20ns	150ns
KMM594000-10	100ns	25ns	180ns

- · Fast Page Mode operation
- · CAS before RAS Refresh capability

RAS-only and Hidden Refresh capability

- TTL compatible inputs and outputs
- Single + 5V ± 10% power supply
- 1024 cycles/16ms refresh
- · JEDEC standard pinout

A0-A10 RAS CAS W

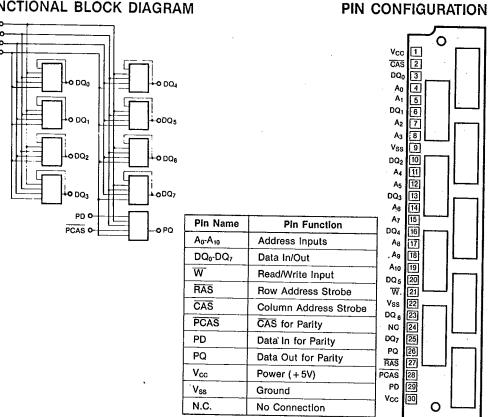
FUNCTIONAL BLOCK DIAGRAM

GENERAL DESCRIPTION

The Samsung KMM594000 is a 4M bit \times 9 Dynamic RAM high density memory module. The Samsung KMM594000 consist of nine KM41C4000J DRAMs in 20-pin SOJ package mounted on a 30-pin glass-epoxy substrate. A 0.22µF decoupling capacitor is mounted under each 4M bit DRAM.

The KMM594000 is a Single In-line Memory Module with edge connections and is Intended for mounting into 30 pin edge connector sockets.





SAMSUNG Electronics

KMM594000

DRAM MODULES

T-46-23-17

ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Rating	Unit	
Voltage on Any Pin Relative to Vss	VIN, VOUT	-1 to +7.0	V	
Voltage on Vcc Supply Relative to Vss	Vcc	-1 to +7.0	V	
Storage Temperature '	T _{stg}	-55 to +150	°C	
Power Dissipation	Po	5.4	W	
Short Circuit Output Current	los	50	mA	

42

 Permanent device damage may occur of "ABSOLUTE MAXIMUM RATINGS" are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS (Voltage referenced to Vss, TA = 0 to 70°C)

Item	Symbol	Min	Тур	Max	Unit
Supply Voltage	Vcc	4.5	5.0	5.5	V
Ground	V _{5S}	0	0	0	V
Input High Voltage	V _{IH}	2.4		V _{cc} +1	V
Input Low Voltage	VIL	- 1.0	-	0.8	v ·

DC AND OPERATING CHARACTERISTICS

(Recommended operating conditions unless otherwise noted.)

Parameter			Min	Max	Unit
OPERATING CURRENT* (RAS, CAS, Address Cycling @t _{RC} = min.)	KMM594000-8 KMM594000-10	loci	-	900 765	mA mA
STANDBY CURRENT ($\overline{RAS} = \overline{CAS} = V_{IH}$)		lcc2	_	18	mA
\overline{RAS} -ONLY REFRESH CURRENT* ($\overline{CAS} = V_{H}$, \overline{RAS} Cycling $@t_{RC} = min.$)	KMM594000-8 KMM594000-10	I _{CC3}	·	900 765	mA mA
FAST PAGE MODE CURRENT* ($\overline{RAS} = V_{IL}$, \overline{CAS} Cycling; $@t_{PC} = min.$)	KMM594000-8 KMM594000-10	Ісся	_	540 450	mA mA
STANDBY CURRENT ($\overline{RAS} = \overline{CAS} = V_{cc} - 0.2V$)		lccs	<u> </u>	9	mA
\overline{CAS} -BEFORE- \overline{RAS} REFRESH CURRENT* (RAS and \overline{CAS} Cycling $@t_{RC} = min.$)	KMM594000-8 KMM594000-10	lccs	-	900 765	mA mA
INPUT LEAKAGE CURRENT (Any input $0 \le V_{IN} \le 6.5V$, all other pins not under test = 0 volts.)		In.	- 90	. 90	μΑ
OUTPUT LEAKAGE CURRENT (Data out is disabled, $0V \le V_{out} \le 5.5V$	t	loL	- 10	10	μA
OUTPUT HIGH VOLTAGE LEVEL (I _{OH} = - 5mA)		V _{он}	2.4		V
OUTPUT LOW VOLTAGE LEVEL (I _{OL} = 4.2mA)		Vol		0.4	v

*Note: Icc1, Icc3, Icc4, and Icc8 are dependent on output loading and cycle rates. Specified values are obtained with the output open. Icc is specified as an average current.



°. 590

42E D 50 7964142 0010484 T 50 SMGK

í

KMM594000

DRAM MODULES

T-46-23-17

CAPACITANCE (T_A = 25°C)

Parameter	Symbol	Min	Max	Unit	
Input Capacitance (A ₀ -A ₁₀)	Cint		50	pF	
Input Capacitance (RAS, CAS, W)	C _{IN2}		60 '	pF	
Input Capacitance (PD, PCAS)	CIN3		10	pF	
Input Capacitance (DQ0-DQ7)	C _{DQ}		15	pF	
Output Capacitance (PQ)	Cq		10	pF	

AC CHARACTERISTICS

AC ELECTRICAL CHARACTERISTICS (0°C≤TA≤70°C, Vcc=5.0V±10%. See notes 1, 2)

Standard Operation	Cumbal	KMM594000-8		KMM594000-10			
	Symbol	Min	Max	Min	Max	Unit	Notes
Random read or write cycle time	t _{RC}	150		180		ns	
Access time from RAS	t _{RAC}		80		100	'ns	3,4
Access time from CAS	tcac		20		25	ns	3,4,5
Access time from column address	tAA		40		50	ns	3,11
CAS to output in Low-Z	t _{CLZ}	5		5	·	ns	3
Output buffer turn-off delay	toff	0	15	0	20	ns	7
Transition time (rise and fall)	t _T	3	50	3	50	ns	2
RAS precharge time	t _{RP}	60		70		ns	•
RAS pulse width	t _{RAS}	80	10,000	100	10,000	ns	
RAS hold time	t _{яsн}	20		25		ns	
CAS hold time	t _{CSH}	80		100		ns	
CAS pulse width	t _{CAS}	20	10,000	25	10,000	ns	
RAS to CAS delay time	t _{RCD}	25	60	25	75	ns	4
RAS to column address delay time	t _{RAD}	15	40	20	50	'ns.	11
CAS to RAS precharge time	t _{CRP}	5		10		ns	
Row address set-up time	t _{ASR}	0		0		ns	
Row address hold time	t _{RAH}	10		15	1	ns	
Column address set-up time	t _{ASC}	0		0		ns	
Column address hold time	t _{CAH}	15		20		ns	
Column address hold referenced to RAS	t _{AR}	60	,	75		ns	6 ·
Column address to RAS lead time	t _{RAL}	40		50		ns	
Read command set-up time	t _{RCS}	0		0	1	ns	
Read command hold referenced to CAS	t _{RCH}	. 0	<u> </u>	0	1	ns	9



KMM594000

DRAM MODULES

T-46-23-17

AC ELECTRICAL CHARACTERISTICS (Continued)

Standard Operation		KMM594000-8		KMM594000-10			
	Symbol	Min	Max	Min	Max	Unit	Notes
Read command hold referenced to RAS	t _{RRH}	0		0		ns	9
Write command hold time	t _{wcн}	15		20		ns	
Write command hold referenced to RAS	t _{WCR}	60		75		ns	6
Write command pulse width	t _{WP}	15		20		ns	
Write command to RAS lead time	t _{RWL}	20		25		ns	
Write command to CAS lead time	t _{CWL}	20		25		ns	
Data-in set-up time	tos	0		. 0		пs	10
Data-in hold time	t _{oн}	15		20		ns	10
Data-in hold referenced to RAS	t _{ohr}	60		75 [·]		ns	6
Refresh period (1024 cyles)	t _{REF}		16	·	16 ·	ms	
Write command set-up time	twcs	0		0		ns '	8
CAS set-up time (C-B-R refresh)	t _{CSR}	10		10		ns	
CAS hold time (C-B-R refresh)	t _{CHR}	30		30		ns	
RAS precharge to CAS hold time	t _{RPC}	0		0		ns	
Access time from CAS precharge	t _{CPA}		50		55	ns	3
Fast page mode cycle time	tec	55		60		ns	
CAS precharge time (Fast page)	tce	10		10		ns	
RAS pulse width (Fast page)	t _{RASP}	80	200,000	100	200,000	ns	

Notes: 1. An initial pause of 200µs is required after power-up followed by any 8 RAS cycles before proper device operation is achieved.

 V_{IH(min)} and V_{IL(max)} are reference levels for measuring timing of input signals. Transition times are measured between V_{IH(min)} and V_{IL(max)} and are assumed to be 5ns for all inputs.

3. Measured with a load equivalent to 2 TTL loads and 100pF.

4. Operation within the t_{RCD(max)} limit insures that t_{RAC(max)} can be met. t_{RCD(max)} is specified as a reference point only. If t_{RCD} is greater than the specified t_{RCD(max)} limit, then access time is controlled exclusively by t_{CAC}.

5. Assumes that $t_{RCD} \ge t_{RCD(max)}$.

6. t_{AB} , t_{WCB} , t_{DHR} are referenced to $t_{RAD(max)}$.

7. This parameter defines the time at which the output achieves the open circuit condition and is not referenced to V_{OH} or V_{OL}.

8. twcs is non restrictive operating parameter. It is included in the data sheet as electrical characteristic only. If twcs≥twcs(min) the cycle is an early write cycle and the data out pin will remain high impedance for the duration of the cycle.

9. Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.

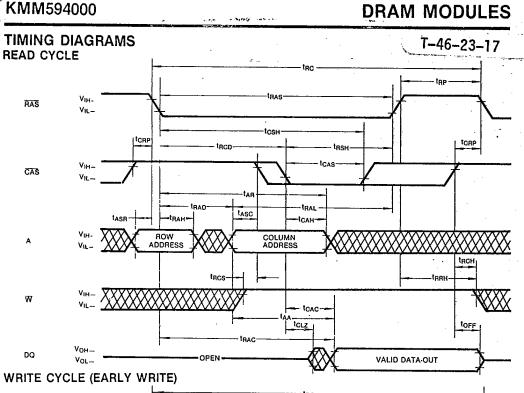
10. These parameters are referenced to the CAS leading edge in early write cycles.

11. Operation within the t_{RAD(max)} limit insures that t_{RAD(max)} can be met. t_{RAD(max)} is specified as a reference point only. If t_{RAD} is greater than the specified t_{RAD(max)} limit, then access time is controlled by t_{AA}.

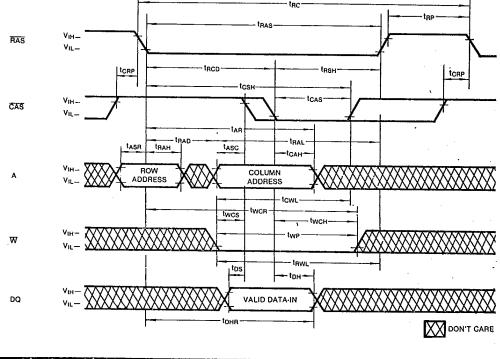


42E D 7964142 0010486 3 📼 SMGK

KMM594000





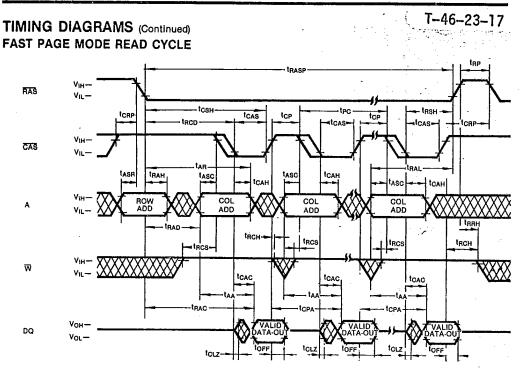


SAMSUNG Electronics

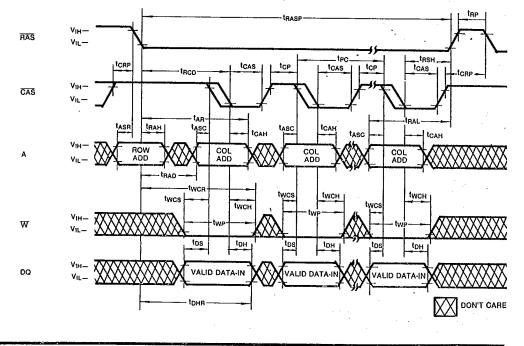
42E D 🗱 7964142 0010487 5 🛤 SMGK

KMM594000

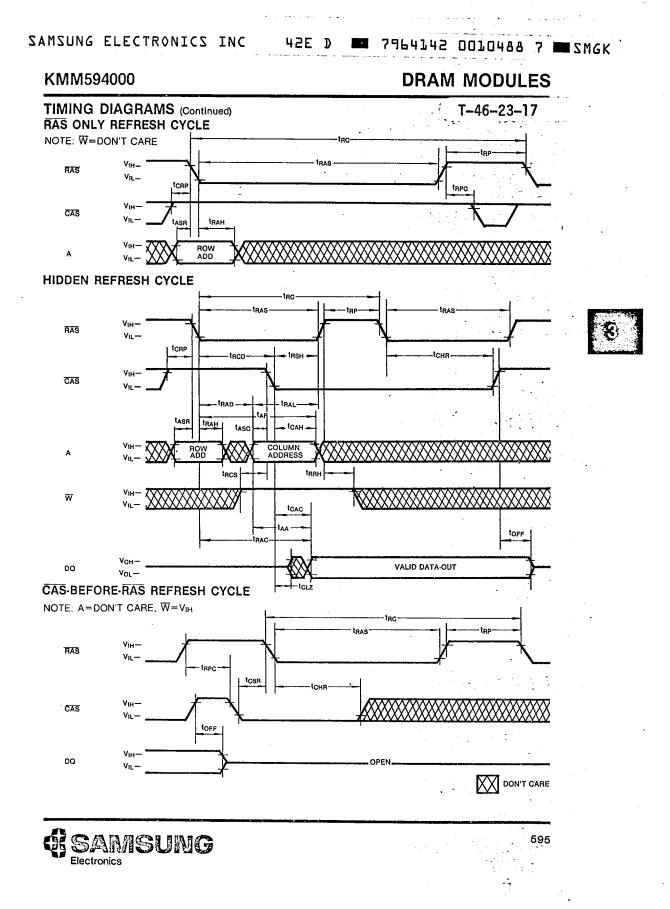
DRAM MODULES



FAST PAGE MODE WRITE CYCLE (EARLY WRITE)



SAMSUNG Electronics



Downloaded from Elcodis.com electronic components distributor



L

42E D 🗰 7964142 0010489 9 🛤 SMGK

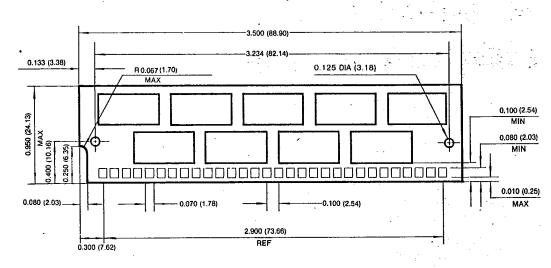


PACKAGE DIMENSIONS

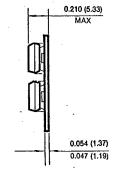
Units: Inches (millimeters)

T-46-23-17

أنغ ...



TOLERANCES: ±0.005 (0.13) UNLESS OTHERWISE SPECIFIED





Downloaded from Elcodis.com electronic components distributor